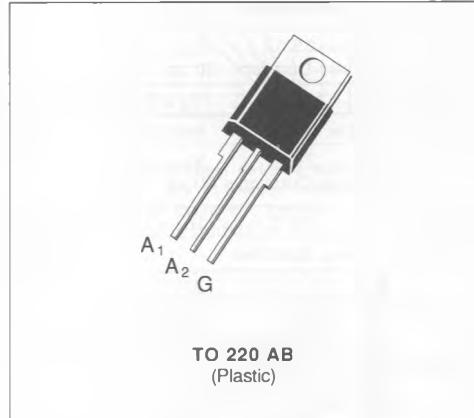


**TRIACS**

- GLASS PASSIVATED CHIP
- EXCELLENT  $(dv/dt)_c > 5 \text{ V}/\mu\text{s}$
- IGT SPECIFIED IN FOUR QUADRANTS
- AVAILABLE IN INSULATED VERSION →  
BTA SERIES (INSULATING VOLTAGE  
2500 V<sub>RMS</sub>) OR IN UNINSULATED VERSION  
→ BTB SERIES
- UL RECOGNIZED FOR BTA SERIES (E81734)


**DESCRIPTION**

New range suited for applications such as phase control and static switching.

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit
I <sub>T(RMS)</sub>	RMS on-state Current (360° conduction angle)	12	A
I <sub>TSM</sub>	Non Repetitive Surge Peak on-state Current (T <sub>j</sub> initial = 25 °C - Half sine wave)	125	A
	t = 10 ms	120	
I <sup>2</sup> t	I <sup>2</sup> t Value for Fusing	72	A <sup>2</sup> s
di/dt	Critical Rate of Rise of on-state Current (1)	10	A/ $\mu$ s
	Repetitive F = 50 Hz	50	
T <sub>stg</sub> T <sub>i</sub>	Storage and Operating Junction Temperature Range	-40 to 150 -40 to 110	°C °C

Symbol	Parameter	BTA/BTB 12-					Unit
		200C	400C	600C	700C	800C	
V <sub>DRM</sub>	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1) I<sub>G</sub> = 500 mA   di<sub>c/dt</sub> = 1 A/ $\mu$ s

(2) T<sub>i</sub> = 110 °C.

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-a)	Junction to Ambient	60	°C/W
R <sub>th</sub> (j-c) DC	Junction to Case for DC	3.3	°C/W
R <sub>th</sub> (j-c) AC	Junction to Case for 360° Conduction Angle (F = 50 Hz)	2.5	°C/W

## GATE CHARACTERISTICS (maximum values)

$$P_{GM} = 40 \text{ W } (t_p = 10 \mu\text{s}) \quad I_{GM} = 4 \text{ A } (t_p = 10 \mu\text{s})$$

$$P_{G(AV)} = 1 \text{ W} \quad V_{GM} = 16 \text{ V } (t_p = 10 \mu\text{s})$$

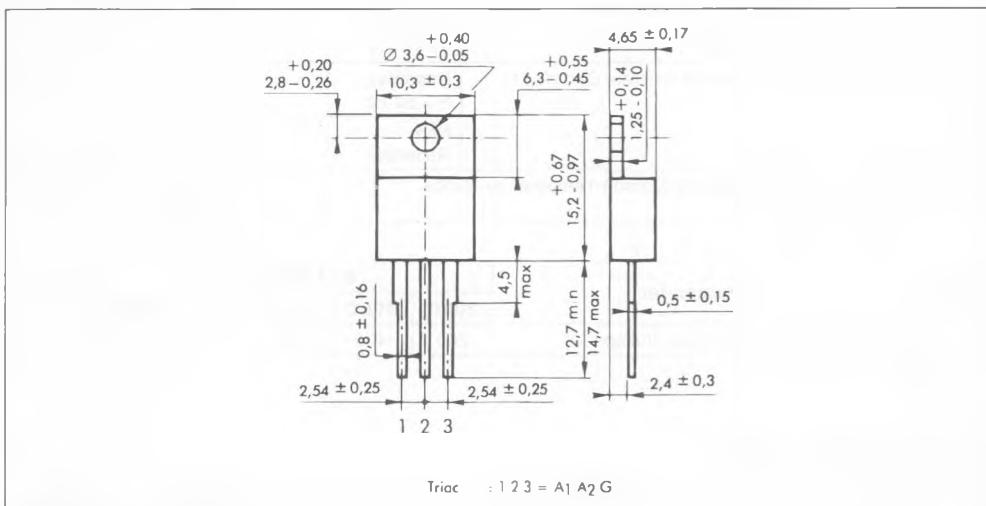
## ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
$I_{GT}$	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	I-II-III			25	mA
	Pulse Duration > 20 $\mu\text{s}$			IV			50	
$V_{GT}$	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	I-II-III-IV			1.5	V
$V_{GD}$			$R_L = 3.3 \text{ k}\Omega$	I-II-III-IV	0.2			V
$I_H^*$	$T_j = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate Open				25	mA
$I_L$	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$I_G = 100 \text{ mA}$	I-III-IV		50		mA
	Pulse Duration > 20 $\mu\text{s}$			II		100		
$V_{TM}^*$	$T_j = 25^\circ\text{C}$	$I_{TM} = 17 \text{ A}$	$t_p = 10 \text{ ms}$				1.5	V
$I_{DRM}^*$	$V_{DRM}$ Specified		$T_j = 25^\circ\text{C}$				0.01	mA
			$T_j = 110^\circ\text{C}$				0.5	
$dv/dt^*$	$T_j = 110^\circ\text{C}$ Gate Open Linear Slope up to $V_D = 67\% V_{DRM}$				100	200		V/ $\mu\text{s}$
$(dv/dt)_c^*$	$T_C = 75^\circ\text{C}$	$V_D = V_{DRM}$	$I_T = 17 \text{ A}$		5			V/ $\mu\text{s}$
$t_{gt}$	$T_j = 25^\circ\text{C}$	$V_D = V_{DRM}$	$I_T = 17 \text{ A}$	I-II-III-IV		2		$\mu\text{s}$
	$I_G = 80 \text{ mA}$		$dI_G/dt = 1 \text{ A}/\mu\text{s}$					

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

## PACKAGE MECHANICAL DATA

TO 220 AB Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g.

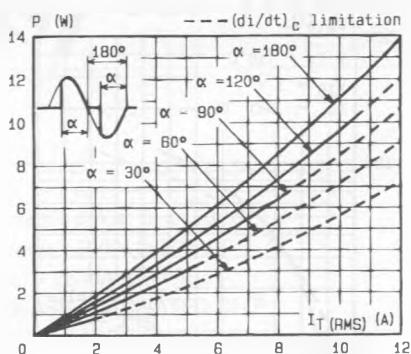


Fig.1 - Maximum mean power dissipation versus RMS on-state current ( $F = 60$  Hz).

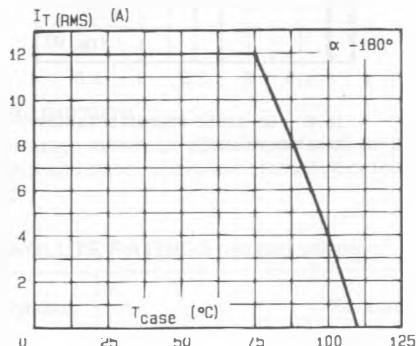


Fig.3 - RMS on-state current versus case temperature.

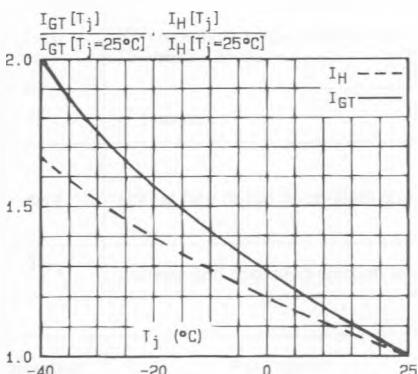


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

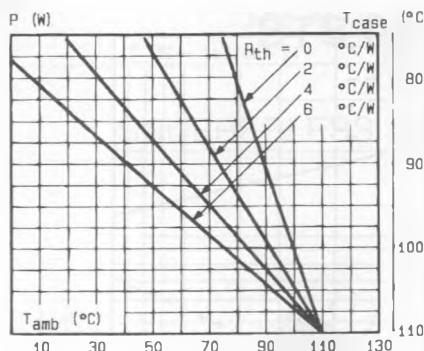


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures [ $T_{amb}$  and  $T_{case}$ ] for different thermal resistances heatsink + contact.

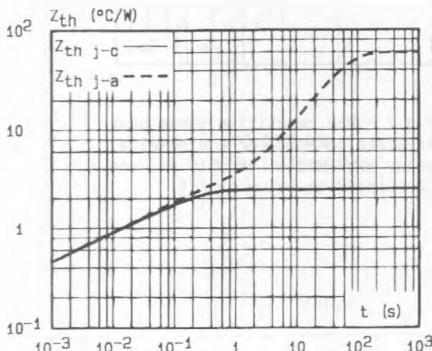


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

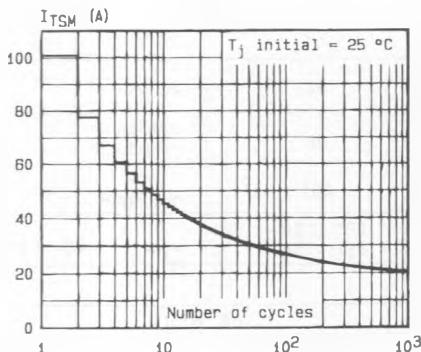


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

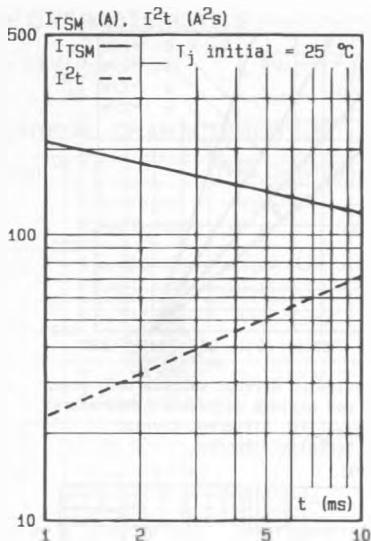


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms. and corresponding value of  $I^2t$ .

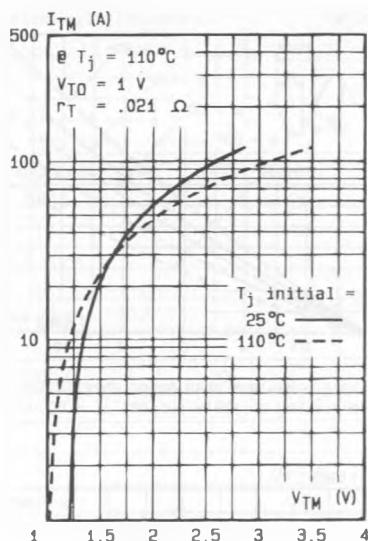


Fig.8 - On-state characteristics (maximum values).